T-1(3mm) BI-COLOR INDICATOR LAMP

Part Number: WP3VEGW

High Efficiency Red Green

Features

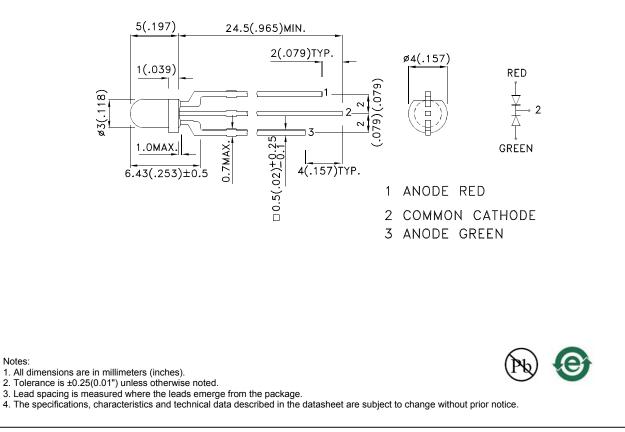
- Uniform light output.
- Low power consumption.
- 3 leads with one common lead.
- Long life solid state reliability.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



SPEC NO: DSAF2640 APPROVED: WYNEC REV NO: V.9A CHECKED: Allen Liu DATE: MAR/02/2013 DRAWN: Q.M.Chen PAGE: 1 OF 7 ERP: 1101003928

Selection Guide Viewing lv (mcd) [2] @ 20mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. 40 15 High Efficiency Red (GaAsP/GaP) *10 *30 WP3VEGW White Diffused 60° 20 40 Green (GaP) *40 *20

Notes

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Green	617 568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	I⊧=20mA
С	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	I⊧=20mA
lr	Reverse Current	High Efficiency Red Green		10 10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm.

Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

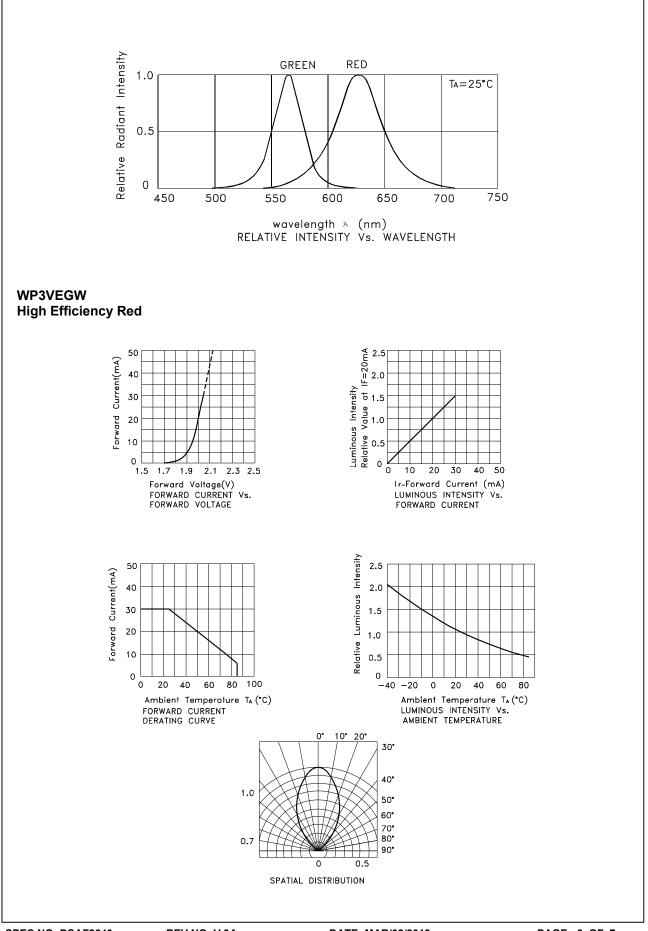
Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage		V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

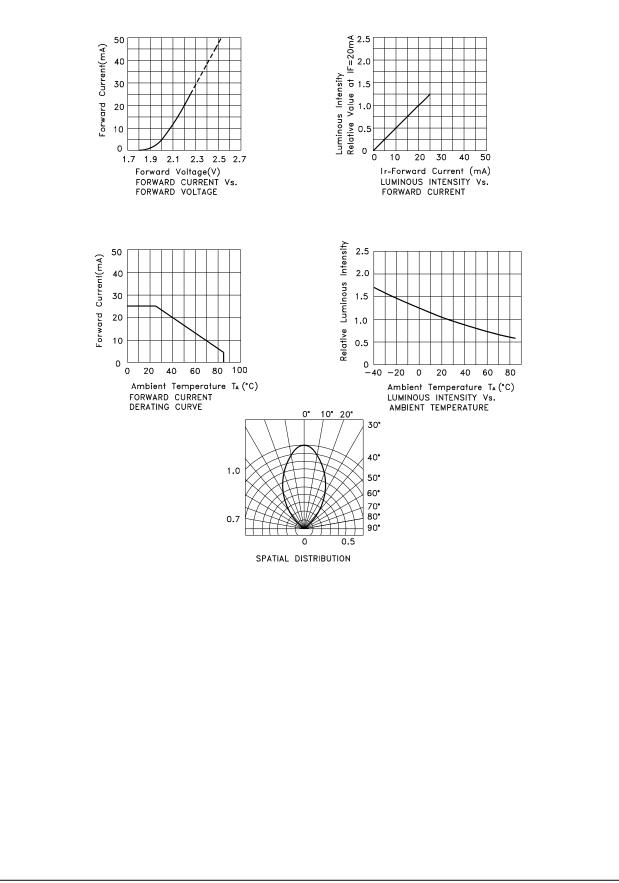
Notes:

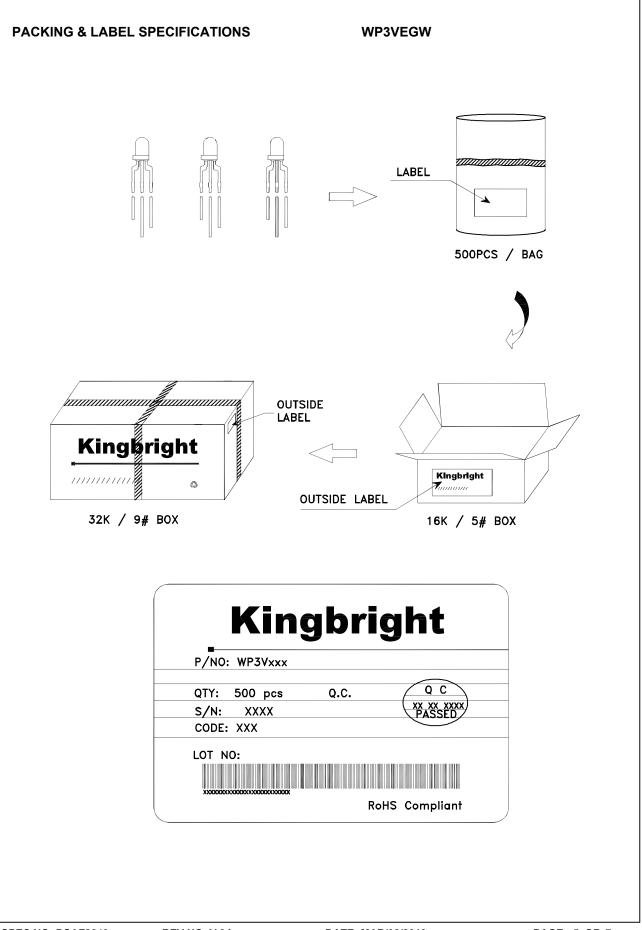
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.
3. 5mm below package base.



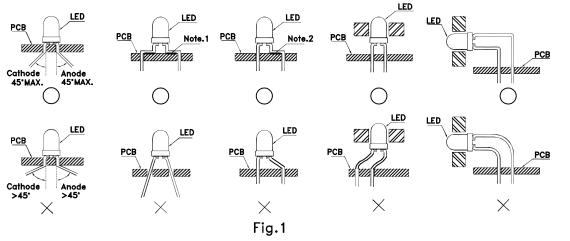
Green





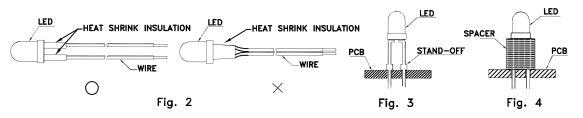
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



" \bigcirc " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

